

21-23 July 2025 **Berlin, Germany** www.ieee-sum.org



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SUMMER TOPICALS MEETING SERIES 2025

Program-at-a-Glance

WEDNESDAY, 23 JULY							
	Concorde A	Concorde B	Vendome A	Vendome B	Odeon A	Opera A	Opera B
	WA1	WB1	WC1	WD1	WE1	WF1	WG1
8:30am - 10:00am	SHINE 8	MATCHA 6	LBL 7	IQPS 8	OA6G 7	NLD 3	8:30am-9:30am PECDP 8
	Reservoir and Recurrent	Broadband Front-Ends and		Quantum Non-linear	FSO/Mmwave Fronthaul	Optical Computing	Sensing
	Computing□	Subsystems II		Photonics II	Infrasture II		
10:00am - 10:30am	BREAK						
	WA2	WB2	WC2	WD2	WE2	WF2	WG2
10:30am -	SHINE 9	МАТСНА 7	LBL 8	10:30am-11:45am IQPS 9	10:30am-12:30pm OA6G 8	NLD 4	10:30am-11:00am PECDP 9
12:00pm	"Charis" Bio-Inspired Unconventional	AMUX and			0 4: 16 4 11:4	New Directions	
	Computing	ADeMUX I		Quantum Communications	Optical Satellite Communications		Advanced Materials
12:00pm - 1:30pm	LUNCH						
1:30pm - 3:00pm	WA3	WB3	WC3			WF3	
	SHINE 10	MATCHA 8	LBL 9			NLD 5	
	Data Sharing for Network Automation	AMUX and ADeMUX II				Laser Modelling	
	1 (ctwork / tutomation	ADCMON II					
3:00pm - 3:30pm	BREAK						
3:30pm - 5:00pm	WA4	WB4					
	SHINE 11	3:30pm-4:30pm MATCHA 9					
	Optical Networks and AI:	Silicon Photonics					
	A Two-Way Evolution						

2025 IEEE Photonics Society Summer Topicals Meeting Series (SUM) 21 - 23 Jul 2025 All times in CEST



Continued from Wednesday, 23 July

2pm

WF3.2 (Invited) - Noise excited feedback delay modes and timing jitter in passively mode-locked lasers

» <u>Lina Jaurigue</u> (Germany)¹, Kathy Ludge (Germany)¹ (1. Institut für

Technische Universität Ilmenau

Ilmenau, Germany)

2:30pm

WF3.3 (Invited) - Emergence of complex pulsing patterns in an excitable microlaser with delayed optical feedback : the role of resonance tongues

» <u>Soizic Terrien</u> (France)¹, Bernd Krauskopf (New Zealand)², Neil G. R. Broderick (New Zealand)², Sylvain Barbay (France)³ (1. LAUM UMR 6613, Institut d'Acoustique - Graduate School

CNRS. Le Mans Université

Le Mans, France, 2. Mathematics Department

The University of Auckland

Auckland, New Zealand, 3. Centre de Nanosciences et de

Nanotechnologies

Université Paris-Saclay, CNRS

Palaiseau, France)

3pm Break & Exhibits

Galerie

3:30pm **wa4** -

WA4: SHINE 11 - Optical Networks and Al: A Two-Way Evolution

Concorde A

Chaired by: Behnam Shariati (Germany) and Mahtab Aghaeipour

(Germany)

3:30pm

WA4.1 (Invited) - The role of optical networks in AI evolution

» <u>Juan Pedro Fernández-Palacios Jimenez</u> (Spain)¹, Pablo Armingol

Robles (Spain)¹ (1. Telefonica)

4pm WA4.2 (Invited) - Scaling Optical Fiber Networks for Environmental Sensing

» <u>Patricia Layec</u> (France)¹, Qiaolun Zhang (Italy)², Khouloud Abdelli (Germany)³, Massimo Tornatore (Italy)², Fabien Boitier (France)¹ (1. Nokia Bell Labs Massy, France, 2. Politecnico di Milano Milano,

Italy, 3. Nokia Bell Labs Stuttgart, Germany)

4:30pm WA4.3 (Invited) - Al-enabled Network Automation in TeraFlowSDN Orchestrated Networks

» <u>Ricard Vilalta</u> (Spain)¹, Lluis Gifre (Spain)¹, Pol Alemany (Spain)¹, Daniel Adanza (Spain)¹, Ricardo Martinez (Spain)¹, Ramon Casellas (Spain)¹, Raul Muñoz (Spain)¹ (1. Centre Tecnològic de Telecomunicacions de Catalunya (CTTC-CERCA), Castelldefels

(Barcelona), Spain)

3:30pm **wB4**-

WB4: MATCHA 9 - Silicon Photonics

Concorde B

Chaired by: Nikolaos-Panteleimon Diamantopoulos (Japan) and

Hidetaka Nishi (Japan)

3:30pm WB4.2 - Monolithically Integrated 2 × 64-Gb/s Silicon Photonic WDM Transmitter

» <u>Yongjin Ji</u> (Korea, Republic of)¹, Dae-Won Rho (Korea, Republic of)¹, Minkyu Kim (Belgium)², Lars Zimmerman (Germany)³, Woo-Young Choi (Korea, Republic of)¹ (1. Department of Electrical and Electropic Engineering

Electronic Engineering

Yonsei University Seoul, South Korea, 2. IMEC

Leuven, Belgium, 3. IHP - Leibniz-Institut für

innovative Mikroelektronik Frankfurt, Germany)

3:45pm

WB4.3 - Silicon Photonic WDM Receiver Architectures for Low-Power Optical I/O

» Xingguo Xiao (Canada)¹, Alireza Geravand (Canada)¹, Leslie A. Rusch (Canada)¹, Wei Shi (Canada)¹ (1. ECE Dept. and Center for Optics, Photonics, and Lasers (COPL), Université Laval, Québec,

Monolithically Integrated 2 × 64-Gb/s Silicon Photonic WDM Transmitter

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Abstract—This paper presents a monolithically integrated 2 \times 64-Gb/s silicon photonic WDM transmitter using micro-ring modulators (MRMs) and EPIC technology, fabricated in a 0.25 μm process. The PAM-4 driver enhances linearity and performance, with measurements confirming stable 64-Gb/s operation.

Keywords—Silicon photonics, WDM transmitter, PAM-4 modulation, monolithic integration, micro-ring modulator.

I. INTRODUCTION

In recent years, the demand for high-bandwidth input/output (I/O) solutions has surged due to the rapid advancements in high-performance computing (HPC) and artificial intelligence (AI) [1-2]. These applications require massive data transfer rates to handle large-scale parallel computations efficiently. Traditional electronic interconnects face fundamental limitations in terms of power consumption, latency, and bandwidth scalability. As a result, silicon photonics has emerged as a promising solution to address these challenges [3].

One of the key techniques in silicon photonics for high-speed optical communication is wavelength-division multiplexing (WDM), which enables multiple optical signals to be transmitted simultaneously over a single optical fiber [4]. This significantly enhances bandwidth efficiency while maintaining a compact footprint and also increases energy efficiency. A crucial component enabling efficient WDM transmission is the microring modulator (MRM), which allows for high-speed, energy-efficient optical modulation with a small footprint and strong integration capabilities. Furthermore, by leveraging monolithic integration through EPIC technology, electronic and photonic components can be seamlessly co-integrated on a single substrate, reducing parasitic losses, improving signal integrity, and minimizing latency [5]. This approach enhances scalability

and simplifies fabrication, making it a compelling choice for high-performance optical interconnects.

In this paper, we present a 2-channel WDM 64-Gb/s PAM4 silicon photonics-based transmitter IC with MRMs, monolithically integrated using an EPIC process for high-bandwidth optical interconnects. The proposed design capitalizes on the benefits of silicon photonics to achieve scalable, low-power, and high-speed data transmission. We will discuss the transmitter design considerations and measurement setup, followed by the output eye diagrams and conclusion.

II. TRANSMITTER DESIGN

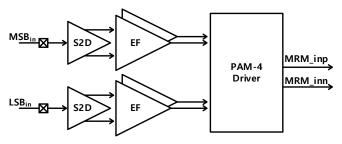


Fig. 1. Block diagram of transmitter.

Fig. 1 illustrates the block diagram of the electrical section of the proposed transmitter. The transmitter architecture consists of source-degenerated differential pairs, emitter follower (EF) buffers, and a cascode configuration for high-voltage operation. Additionally, the system utilizes a single-ended to differential (S2D) conversion stage for differential signaling. The output of the S2D stage is fed into EF buffers, which provide biasing and prevent loading effects, ensuring stable signal propagation into the PAM-4 driver.

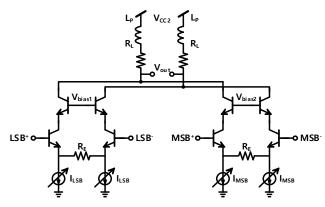


Fig. 2. Block diagram of PAM-4 driver.

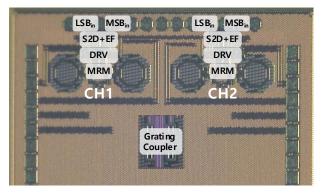


Fig. 3. Chip photo.

Fig. 2 shows the circuit diagram of PAM-4 driver. The driver employs source degeneration to improve linearity and bandwidth while maintaining power efficiency. A cascode topology enables high-voltage operation with a 4.5 V supply while reducing voltage stress on active components. The output stage incorporates load resistors R_L of 80 Ω . Additionally, inductive peaking L_P of 200 pH extends the driver bandwidth from 29-GHz to 40-GHz. To compensate for the DC nonlinearity of the MRM, the ratio of the MSB and LSB currents is adjusted. This enables pre-distortion through RLM, effectively linearizing the MRM response.

III. MEASUREMENT SETUP AND RESULTS

Fig. 3 presents the chip photo of the fabricated WDM transmitter, which is implemented using IHP's 0.25 μ m SG25H5 process. The transmitter consists of two independent channels which are CH1 and CH2, each integrating a PAM-4 driver and a MRM. The input MSB and LSB signals drive the PAM-4 transmitter, modulating the MRM. The gap between the MRM and the waveguide, is 240 nm for channel 1 and 260 nm for channel 2.

Fig. 4 illustrates the measurement setup of the WDM transmitter. A tunable laser source provides a continuous-wave (CW) optical signal, which is polarization-controlled before being coupled into the chip. The transmitter is driven by an external 2-channel pattern generator supplying MSB and LSB signals. The modulated optical signals are coupled out via a grating coupler and transmitted through an optical fiber. The grating coupler introduces an insertion loss of approximately 4.5

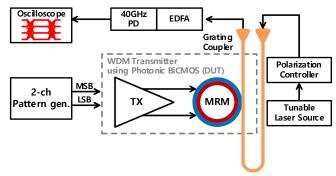


Fig. 4. Measurement setup.

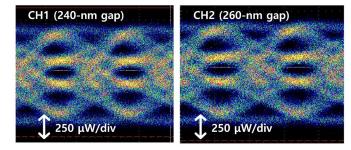


Fig. 5. 64-Gb/s PAM-4 eye diagrams of each channel.

dB. An erbium-doped fiber amplifier (EDFA) compensates for optical losses before detection by 40 GHz photodetector (PD). The electrical output is analyzed using an oscilloscope to assess signal integrity, eye diagrams, and overall modulation performance. Fig. 5 shows the measured 64-Gb/s PAM-4 eye diagrams for channel 1 and channel 2. Both channels exhibit reliable operation at the target data rate.

ACKNOWLEDGMENT

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